## Device Opportunities for Beyond CMOS: A System Perspective

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## Question

- How will semiconductor nanoscale technology impact different information-processing and computing approaches?
* Can emerging memory and logic technologies impact VIA2020?


## CMOS scaling on track to obtain physical limits for electron devices

George Bourianoff / Intel


System reliability costs: All $N$ devices in the logic system operate correctly $E_{b}=f\left(N_{t t}\right)$

$$
N_{t r} \uparrow \rightarrow E_{b} \uparrow
$$

Fan-Out costs: The need of each device to communicate to several others Long communication costs: Communication at distance is a very costly process $\} N_{e l} \uparrow$

## Minimum number of electrons in interconnect line for communication and fan-out

$$
\Pi=\left(1-\left(1-\frac{a}{L}\right)^{N}\right)^{N-\text { number of electrons }} \frac{F \text {-fan-out }}{} \frac{\begin{array}{|}
\frac{L}{a}=k \\
\Pi=\frac{1}{2}
\end{array}}{\square} \frac{1}{2}=\left(1-\left(1-\frac{1}{k}\right)^{N}\right)^{F}
$$




## Energy costs for fan-out: 2D vs.3D



For probability of correct communication >50\%

Fan Out
= More Computation
$E \sim N \cdot E_{b}=N \cdot e \cdot V_{d d}$

$$
E \sim 3 \cdot 1.6 \cdot 10^{-19} \cdot 0.3=1.4 \cdot 10^{-19} J=35 k_{B} T
$$



Generic topology of a 3D binary switch

## Emerging Research Logic Devices 2003 ITRS ERD Chapter

|  | $\checkmark$ | " | Him | 」 $\begin{array}{r}\text { ¢ } \\ \text { * }\end{array}$ | $-\llbracket \cdot \square$ |  | - | $\stackrel{+}{\square}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Device | FET | RSFQ |  | Resonant Tunneling Devices | SET |  | $Q C A$ | Spin transistor |
| Cell Size | 100 nm | $0.3 \mu \mathrm{~m}$ | 100 nm | 100 nm | 40 nm | Not known | 60 nm | 100 nm |
| Density $\left(\mathrm{cm}^{-2}\right)$ | 3E9 | 1E6 | 3E9 | 3E9 | 6E10 | 1E12 | 3E10 | 3E9 |
| Switch Speed | $\begin{gathered} 700 \mathrm{GH} \\ \mathrm{z} \end{gathered}$ | 1.2 THz | Not known | 1 THz | 1 GHz | Not known | 30 MHz | 700 GHz |
| Circuit Speed | 30 GHz | $\begin{gathered} 250- \\ 800 \mathrm{GHz} \end{gathered}$ | 30 GHz | 30 GHz | 1 GHz | $<1 \mathrm{MHz}$ | 1 MHz | 30 GHz |
| Switching <br> Energy, J | $2 \times 10^{-18}$ | $>1.4 \times 10^{-17}$ | $2 \times 10^{-18}$ | $>2 \times 10^{-18}$ | $>1.5 \times 10^{-17}$ | $1.3 \times 10^{-16}$ | $>1 \times 10^{-18}$ | $2 \times 10^{-18}$ |
| Binary Throughput, GBit/ns/cm ${ }^{2}$ | 86 | 0.4 | 86 | 86 | 10 | N/A | 0.06 | 86 |

System driven evaluation: 1D structures appear to be promising

## Summary Comparison of Electronic, Spin and Optical State Computing

|  | Lower bound (Impractical Limit) |  |  |
| :---: | :---: | :---: | :---: |
| Mechanism | Energy | Size |  |
| Electronic | $3 k_{B} T$ | 1 nm | Practical limit $-3-5 \mathrm{~nm}$ |
| Spin | $70 k_{B} T$ | 7 nm | Practical limit >20 nm |
| Optical | $3600 k_{B} T$ | 20 nm | Practical limit >90 nm |

## Two-well bit - Universal Device Mode: ${ }^{33}$



Generic Floorplan of a binary switch

Device density

1) Upper Bound

$$
n_{\max }=\frac{1}{8 a^{2}}
$$

2) IC (ITRS)

$$
n_{M P U}=\frac{1}{(20 a)^{2}}
$$

## Can we have

 smaller tile?
## How can we go below 5 nm ?

2006 hypothesis: Devices having feature sizes less than 5 nm should utilize particles whose mass is greater than the mass of an electron. Below about 5 nm , the mass of information-bearing particle should exceed free electron mass.

This conclusion resulted from the Heisenberg limit on device size

$$
L_{\min }=\frac{\hbar}{\sqrt{2 m E_{b}}}
$$

$$
L \sqrt{m}=\text { const }
$$



$$
t_{s w}=\frac{L}{v}=L \sqrt{\frac{m}{2 E}} t_{s w} \sim L \sqrt{m}
$$

Heavy-electron materials?
or
Moving atoms instead of moving electrons?

## Moving atoms I: ‘Atomic Relay’

Atomic-scale switch, which opens or closes an electrical circuit by the controlled reconfiguration of silver atoms

OFF
 within an atomic-scale junction.

Such 'atomic relays' operate at room temperature and the only movable part of the switch are the contacting atoms, which open and close a nm-scale gap.

$$
\begin{aligned}
& \text { Small ( } \sim 1 \mathrm{~nm} \text { ) } \\
& \text { Fast ( } \sim 1 \mathrm{~ns} \text { ) - projection } \\
& \text { Low voltage (<1V) }
\end{aligned}
$$

Nature 433, 47-50 (6 January 2005)

## Quantized conductance atomic switch

K. Terabe, T. Hasegawa, T. Nakayama and M. Aono

## Moving atoms II: ‘Memristor’


D. B. Strukov, G. S. Snider, D. R. Stewart \& R. Stanley Williams, Nature 453, May 2008, 80-83

## NANODEVICES

## Charge of the heavy brigade

Hybrid devices that rely on the movement of both electrons and ions might one day challenge conventional silicon electronics by exploiting both classical and quantum electron transport.

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The search for new ways to process information is unearthing some interesting alternatives to the traditional semiconductor approach, which will eventually reach fundamental limits imposed by the laws of physics. One such device is the 'memristor' (short for memory resistor) that was recently reported by Stanley Williams and co-


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$\rightarrow \underset{\sim}{c}$
V. V. Zhirnov and R. K. Cavin, Nature Nanotechnology, July 2008

## Moving Atoms III: Nanowire phasechange memory

- Nanowire phase-change memory
M. Meyyappan et al, APPLIED PHYSICS LETTERS 91 SEP 242007
- Goal:
* Low-Voltage Non-volatile memory to replace SRAM
- Quasi 1D (e.g. nanowire) components


## Technology Goal

Develop low-power high-density data storage using nanomaterial array, enabling $10^{2} \sim 10^{3} \mathrm{X}$ faster R/W, 10~15X lower write voltage, and 10~100X higher integration density

## Technology Challenges

$\square$ Super-scalable R-switching nanowire memory
$\square$ Large-scale self-assembly / patterned assembly
$\square$ 3-D integration / selecting device

Next-generation highly scalable, ultra-low power, resistive switching non-volatile memory chip technology based on phase-change nanomaterials

## Technical Approach

- 3-D vertical nanowire array
- Non-charge-based (radiationfree)
. Significantly reduced thermal writing energy ( $10^{2} \sim 10^{3} \mathrm{X}$ )
- Super scalable memory cell
- Reduced thermal interference
- Multi-layer stacking for high integration density
- Binary or analog data storage
$\square$ Low temperature assembly compatible with Si-IC platform



## Anticipated Performance Metrics

- Target 0.5~1 V R/W operation
- $1 \mu \mathrm{~A} / \mathrm{cell}$ reset current

```
- 1 TB/cm2 density
-<10-12 J/bit switch energy
```

$$
\begin{aligned}
& \text { - Less than } 10 \text { ns write time } \\
& \text { - } 10^{10} \text { cycle endurance } \\
& \hline
\end{aligned}
$$

## Moving atoms IV: lons in liquid electrolytes

## Ions in liquid electrolytes play an important role in biological information processors such as the brain

In the human brain, the distribution of $\mathbf{C a}$ ions in dendrites may represent a crucial variable for processing and storing information.

Ca ions enter the dendrites through voltage-gated channels in a membrane, and this leads to rapid local modulations of calcium concentration within dendritic tree

C. Koch, "Computation and single neuron",

Based on the brain analogy, the binary state can be realized by a single ion that can be moved to one of two defined positions, separated by a membrane (the barrier) with voltage-controlled conductance

Ions are heavy, but brain seems to use them efficiently!

## Key Messages

- 1D structures could be enabling!

1D logic devices to reduce fan-out costs

- Topology optimization for energy reduction
- Quasi 1D (e.g. nanowire) components arranged in 3D structures
- It appears that, in principle, scaling of devices can continue well below the electron limit
* Below about 5 nm we need particles whose mass exceeds that of the electron

